

PRELIMINARY

Notice ; This is not a final specification.
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DESCRIPTION

The M61130FP is a semiconductor integrated circuit consisting of Tuner signal processing for NTSC color TV sets and VCRs. The circuit includes Mixer circuit in Tuning system, Oscillator circuit, PLL frequency synthesizer and VIF/SIF, which permits a smaller tuner system.

FEATURES

- VIF/SIF
 - Inter carrier type for NTSC
 - Coil-less VCO
 - Adjustment free AFT
 - High-speed IF AGC
- PLL
 - Low phase noise and High-speed lock-up
 - Built-in band switch driver (4 port)
 - I²C bus control
 - Available for both XO and external reference
- Mixer/Oscillator
 - Built-in U&V oscillator and mixer
 - Built-in UV band switch

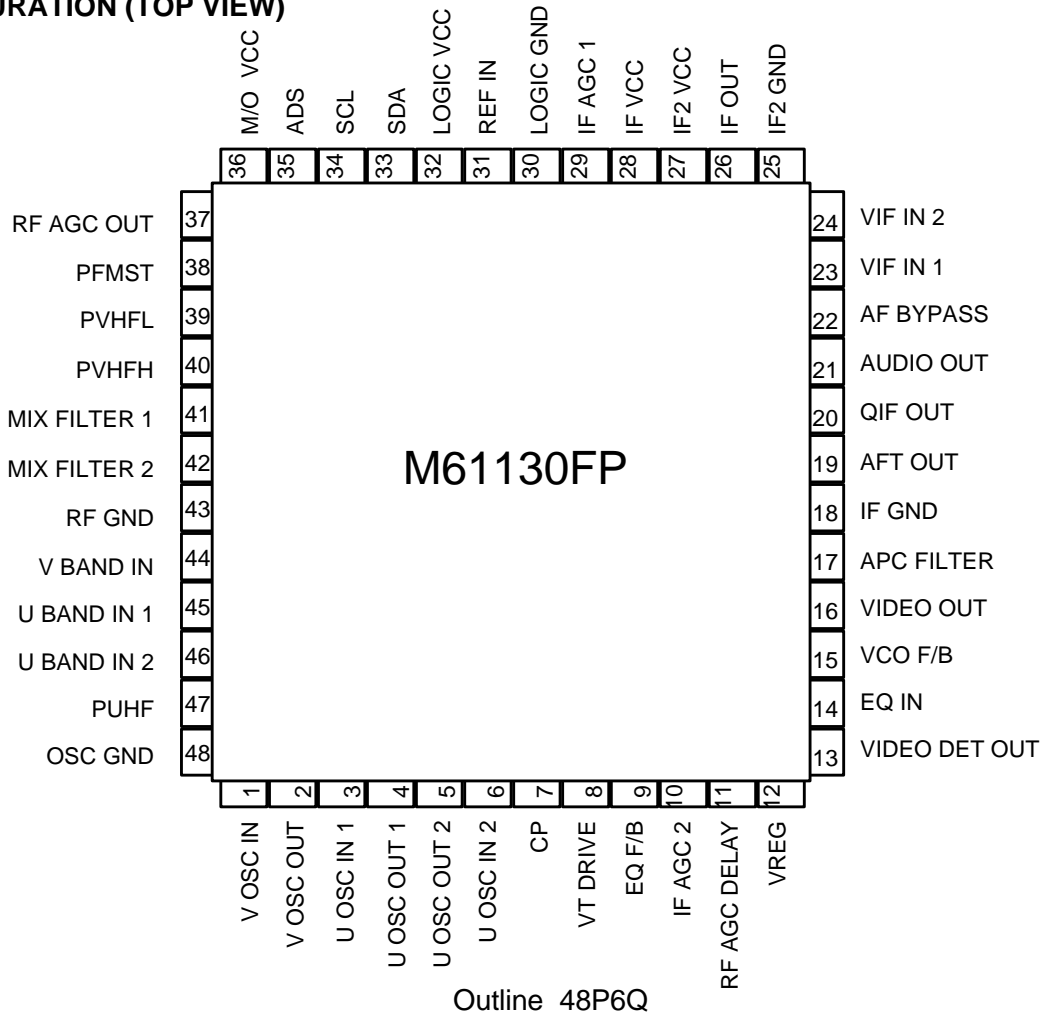
APPLICATION

TV, VTR

RECOMMENDED OPERATING CONDITIONS

Supply voltage range.....4.75 to 5.25V
Recommended supply voltage.....5.0V

PIN CONFIGURATION (TOP VIEW)

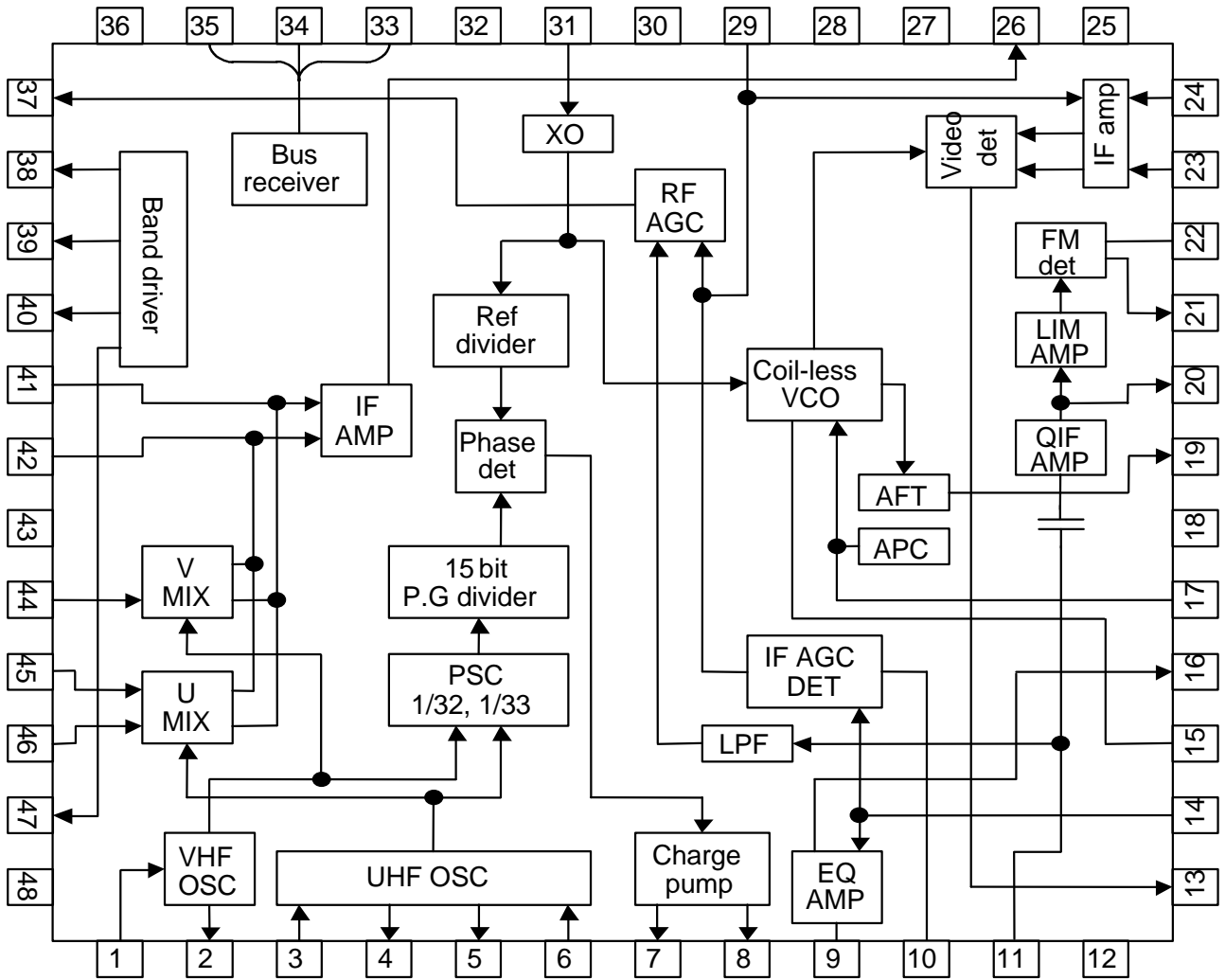


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TUNER SINGLE CHIP

BLOCK DIAGRAM



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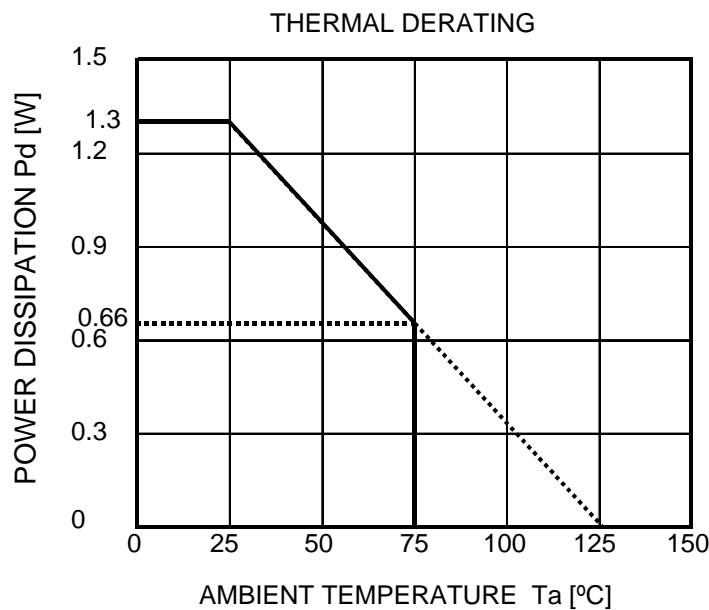
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TUNER SINGLE CHIP

ABSOLUTE MAXIMUM RATINGS (Ta=25°C, unless otherwise noted)

Symbol	Parameter	Rating	Unit
Vcc	Supply Voltage	6.0	V
Pd	Power Dissipation	658	mW
Topr	Operating temperature	-20 to +75	°C
Tstg	Storage temperature	-40 to +150	°C

TYPICAL CHARACTERISTICS

**ELECTRICAL CHARACTERISTICS** (Ta=25°C, unless otherwise noted)

Symbol	Parameter	Measure Point	Test conditions	Limits			Unit
				Min	Typ	Max	
IF Icc	IF Vcc current	28		-	70	84	mA
MO Icc	M/O Vcc current	36		-	21	25	mA
Log Icc	Logic Vcc current	32	Port output off	-	14	20	mA
Log Icc(U)	Logic Vcc current(UHF)	32	I _{BS} =-22mA	-	40	46	mA
Log Icc(V)	Logic Vcc current(VHF)	32	I _{BS} =-25mA	-	43	50	mA
Log Icc(F)	Logic Vcc current(FM)	32	I _{BS} =-15mA	-	32	38	mA
Ibavideo	Video out bias current	16		1.4	1.9	2.4	mA
IbaAudio	Audio out bias current	21		1.0	1.3	1.6	mA
IbaQIF	4.5MHz QIF out bias current	20		0.9	1.2	1.5	mA
Vreg	Regulator voltage	12		2.65	2.8	2.95	V
fxosc	X'tal frequency	31	PLL function range	3.0	4.0	4.8	MHz
frefin	Ref. signal frequency	31	PLL function range	3.0	4.0	5.0	MHz
Vifrefin	Ref. signal input level	31		50	-	600	mVp-p

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TUNER SINGLE CHIP

ELECTRICAL CHARACTERISTICS (cont.)

M/O

Symbol	Parameter	Measure Point	Test conditions	Limits			Unit
				Min	Typ	Max	
Band VHF Mixer			RL=75				
GpVHF1	Conversion gain1	26,44	fRF=57.5MHz	16	19	22	dB
GpVHF2	Conversion gain2	26,44	fRF=357.5MHz	16	19	22	dB
NFVHF	Noise figure	26,44	fRf=57.5~357.5MHz		11		dB
CM1VHF	1% cross modulation1	26,44	fRF=55.25MHz	90			dBμV
CM2VHF	1% cross modulation2	26,44	fRF=361.25MHz	90			dBμV
Band UHF Mixer			RL=75				
GpUHF1	Conversion gain1	26,45,46	fRF=369.5MHz	26	29	32	dB
GpUHF2	Conversion gain2	26,45,46	fRF=803.5MHz	26	29	32	dB
NFUHF	Noise figure	26,45,46	fRF=369.5~803.5MHz		10		dB
CM1UHF	1% cross modulation1	26,45,46	fRF=367.25MHz	80			dBμV
CM2UHF	1% cross modulation2	26,45,46	fRF=801.25MHz	80			dBμV
Band VHF Oscillator							
foVHF	Operation range	26		101		407	MHz
fosc(v)	Supply voltage drift	26	Vcc=5%		100		KHz
foV(t)	SW ON drift	26	3sec~3min after SW ON		200		KHz
Band UHF Oscillator							
foUHF	Operation range	26		413		847	MHz
fosc(U)	Supply voltage drift	26	Vcc=5%		100		KHz
foU(t)	SW ON drift	26	3sec~3min after SW ON		200		KHz

PLL

Symbol	Parameter	Measure Point	Test conditions	Limits			Unit
				Min	Typ	Max	
Input terminals							
ViH	Hi input voltage	33,34		3.0	-	Vcc+0.3	V
ViL	Lo input voltage	33,34		-	-	1.5	V
IiH1	Hi input current	33,34	Vcc=5.5V,Vi=4.0V	-	-	10	μA
IiL1	Lo input current	33,34	Vcc=5.5V,Vi=0.4V	-	-	-10	μA
SDA output							
VsiL	Lo output voltage	34	Vcc=5.5V,Io=3mA	-	-	0.4	V
IsLK	Leakage current	34	Vcc=5.5V,Vo=5.5V	-	-2	-10	μA
ADS input							
IiH2	Hi input current	35	Vcc=5.5V,Vi=5.0V	-	-	10	μA
IiL2	Lo input current	35	Vcc=5.5V,Vi=1.5V	-	-15	-30	μA
Band output							
VoBS1	Output voltage1	39,40	Vcc=5.0V,Io=-25mA PVHFL,PVHFH	4.6	4.8	-	V
VoBS2	Output voltage2	47	Vcc=5.0V,Io=-22mA,PUHF	4.6	4.8	-	V
VoBS3	Output voltage3	38	Vcc=5.0V,Io=-5mA,PFMST	4.6	4.8	-	V
IoBSLK	Leakage current	38,39,40 47	Vcc=5.5V,Output is OFF	-	-	10	μA
Charge pump							
IcpH	Hi output current	7	Vcc=5.5V,Vo=2.5V,CP=1	160	270	360	μA
IcpL	Lo output current	7	Vcc=5.5V,Vo=2.5V,CP=0	50	70	110	μA
IcpLK	Leakage current	7	Vcc=5.5V,Vo=5.5V,T2,T1=0	-	-	50	nA

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ELECTRICAL CHARACTERISTICS (cont.)

VIF/SIF

Symbol	Parameter	Measure Point	Test conditions	Limits			Unit
				Min	Typ	Max	
VoDET	Video output level	16	IF 77.78%, 15.7KHz AM, 90dBμ	1.1	1.3	1.5	Vp-p
Vsync	Sync tip voltage	13		1.1	1.3	1.5	V
VSN	Video S/N	13	with 6MHz LPF, 90dBμV	48	50	-	dB
BW	Video out freq. response	16	loss 6MHz	-	3	5	dB
VINMIN	Input sensitivity	13,23,24	-3dB down point		45	49	dBμV
VINMAX	Max. IF input	13,23,24	+3dB up point	101	105	-	dBμV
GR	AGC range	-		54	60	-	dB
V10	IF AGC voltage	10		2.7	2.9	3.1	V
V10L	IF AGC min. voltage	10	110dBμV	1.9	2.1	2.3	V
CL-U	Capture range U	23,24	45.75MHz, 90dBμV	1.5	2.5	-	MHz
CL-L	Capture range L	23,24	45.75MHz, 90dBμV	1.5	1.9	-	MHz
D/G	D/G	13		-	3	5	%
D/P	D/P	13		-	3	5	deg
RINV	VIF input impedance	23,24	DC	-	2k	-	
CINV	VIF input capacitance	23,24	40MHz	-	5	-	pF
foC1	AFT Center freq. 45.75MHz	19,23,24	pin19 voltage = Vcc/2	-30	fo	+30	KHz
foC2	AFT Center freq. 58.75MHz	19,23,24	pin19 voltage = Vcc/2	-30	fo	+30	KHz
V19H	Hi output voltage	19	Vcc=5.0V	4.3	4.7	5.0	V
V19L	Lo output voltage	19		0	0.3	0.7	V
V19C	Center voltage	19	45.75MHz	2.3	2.5	2.7	V
μ	Sensitivity	19	360K //360K	10	24	36	mV/KHz
VRFH	RFAGC Hi output voltage	37	open	4.4	4.7	5.0	V
VRFLV	RFAGC Lo output voltage	37	open	0	0.3	0.6	V
RFDLY	RFAGC Delay point	23,24,37	@11pin 2V	87	90	93	dBμV
VoAF	Audio out level	21	4.5MHz±25kHz 1kHz	660	770	880	mVrms
THDAF	Audio out THD	21	4.5MHz±25kHz 1kHz	-	0.2	0.9	%
AFSN	Audio out S/N	21	4.5MHz±25kHz 1kHz	54	57	-	dB
LIM	Limiting sensitivity	11,21		-	50	55	dBμV
AMR	AMR	21		50	55	-	dB
VoQIF	QIF output	20		94	100	-	dBμV

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TUNER SINGLE CHIP

CONTROL TABLE

VIF frequency select

	VIF frequency	20pin condition
US	45.75 MHz	none
JAPAN	58.75 MHz	pull down (1.5K)

Ref input

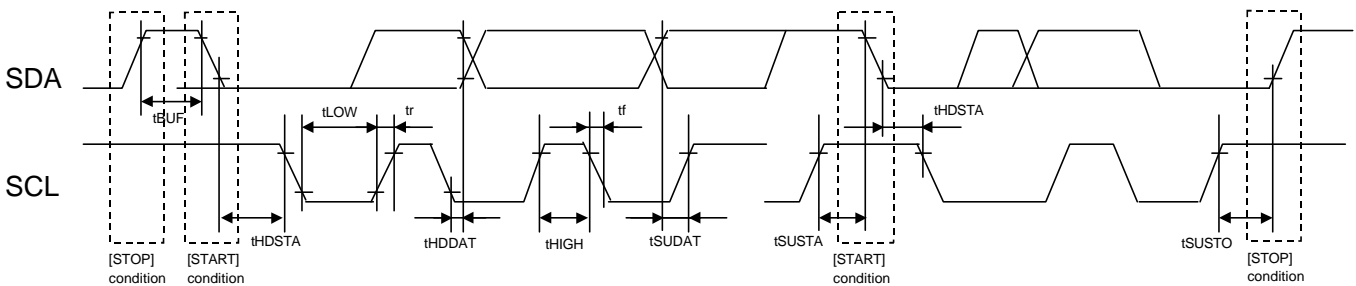
Ref in (31pin)	31pin condition
INT	none
EXT	pull down (2K)

BUS CONTROL

1)ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Measure Point	Test conditions	Limits			Unit
				Min	Typ	Max	
fSCL	Clock frequency	33		0	100	400	KHz
tBUF	Bus free time	34		1.3	-	-	µsec
tHDSTA	Data hold time	34		0.6	-	-	µsec
tLOW	SCL LOW hold time	33		1.3	-	-	µsec
tHIGH	SCL HIGH hold time	33		0.6	-	-	µsec
tSUSTA	Set up time	33,34		0.6	-	-	µsec
tHDDAT	Data hold time	33,34		0	-	-	µsec
tSUDAT	Data set up time	33,34		100	-	-	nsec
tR	Rise time	33,34		-	-	300	nsec
tF	Fall time	33,34		-	-	300	nsec
tSUSTO	Set up time	33		0.6	-	-	µsec

Timing Chart 1



2)Setting Data

The input information consisting of data of 2 or 4 bytes after chip address is received into I²C bus receiver. The definition of bus protocol admitted is shown as below.

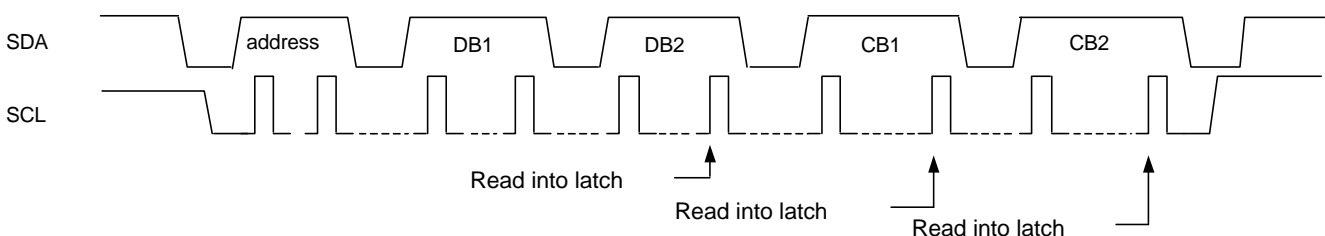
Mode_1	STA	CA	DB1	DB2	CB1	CB2	STO	STA	: Start condition
Mode_2	STA	CA	CB1	CB2	DB1	DB2	STO	STO	: Stop condition
Mode_3	STA	CA	DB1	DB2	STO			CA	: Chip address
Mode_4	STA	CA	CB1	CB2	STO			DB1	: Divider data byte 1
								DB2	: Divider data byte 2
								CB1	: Control data byte 1
								CB2	: Band data byte 2

The information of 5 bytes required for circuit operational chip address, control data and band SW data of 2 bytes and divider data of 2 bytes. After the chip address input, 2 or 4 bytes can be received. Function bit is contained in the first and the third data byte to distinguish between divider and 'control data/band SW data', with "0" going ahead of divider data, and "1" going ahead of control data/band SW data'.

The timing of Writing data for bus protocol Mode is shown in the figure below. Divider data uses 15 bits and is read in at the rise of the eighth clock bit of the second byte divider data (D2).

Control data (CB) and band SW-data (BB) are each read in at the rise of their eighth clock bit.

Timing Chart 2



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TUNER SINGLE CHIP

Write mode data format

Byte	MSB						LSB			
Address Byte (CA)	1	1	0	0	0	0	MA1	MA0	R/W=0	A
Divider Byte1 (DB1)	0	N14	N13	N12	N11	N10	N9	N8	N8	A
Divider Byte2 (DB2)	N7	N6	N5	N4	N3	N2	N1	N0	N0	A
Control Byte (CB1)	1	CP	T2	T1	T0	Rsa	Rsb	OS	OS	A
Band Byte (CB2)	RE	AFT	X	X	PUHF	PFMST	PVHFH	PVHFL	PVHFL	A

MA1,MA0 : Programmable Address Bit

Address input voltage applied to ADS [V]	MA1	MA0
0 to 0.1×Vcc	0	0
Always Valid	0	1
0.4×Vcc to 0.6×Vcc	1	0
0.9×Vcc to Vcc	1	1

N14 to N0 : How to set division ratio of the programmable divider

$$\text{Division ratio N: } N=N14(2^{14})+N13(2^{13})+ \dots +N0(2^0)$$

$$\text{Range of division ratio N: } N=1,024 \text{ to } 32,767$$

$$\text{Frequency of VCO } f_{vco}: f_{vco}=f_{ref} \times N$$

CP : Set up the charge pump current

CP	Charge pump current
0	70µA
1	270µA

In the case of setting current 270µA, when PLL is locked, charge pump current is automatically switched to CP=0 (70µA).

T2,T1,T0 : Set up for test mode

CP	T2	T1	T0	Charge pump	Test output	Test SW	Mode
0	0	0	X	CP switched off	-	OFF	Normal mode
1	0	0	X	CP switched on	-	OFF	Normal mode
X	0	1	X	High impedance	-	OFF	Test mode
0	1	1	0	Sink, CP current "Low"	-	OFF	Test mode
1	1	1	0	Sink, CP current "High"	-	OFF	Test mode
0	1	1	1	Source, CP current "Low"	-	OFF	Test mode
1	1	1	1	Source, CP current "High"	-	OFF	Test mode
0	1	0	0	High impedance	fREF	OFF	Test mode
1	1	0	X	CP switched on	-	ON	Test mode
0	1	0	1	High impedance	f1/N	OFF	Test mode

Note : fREF and f1/N is available on pin PFMST

: Test SW is for the mix filter damping switch

Rsa,Rsb : Set up tuning step

Rsa	Rsb	Division ratio	tuning step frequency
0	1	1/128	31.25KHz
1	1	1/64	62.5KHz
X	0	1/80	50.0KHz

@4MHz X'tal

OS : Set up drive output

OS	Drive output	Mode
0	ON	Normal mode
1	OFF("L")level	Test mode

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TUNER SINGLE CHIP

RE: Select of Reference frequency for automatic adjustment of VIF VCO free-running frequency.

RE	Reference frequency
0	3.58MHz
1	4.00MHz

AFT:Set up AFT mute

AFT	AFT mute voltage
0	Low
1	center

PFMST , PUHF , PVHFL,PVHFH : PORT

FMST,PUHF,PVHFL,PVHF	Output
0	OFF
1	ON

PNP open collector output. When PUHF is "OFF",
Mixer and Oscillator active VHF mode.

Read mode data format

Byte	MSB							LSB	
Address Byte	1	1	0	0	0	MA1	MA0	R/W=1	A
Status Byte	POR	FL	ACPS	X	X	X	X	X	A

X: 0 or 1 Don't care

POR: Power on reset flag. Output is "1" at power-on

FL: Lock detector flag. Output is "1" at locked, output is "0" at unlocked.

ACPS: Automatic charge pump current flag. Output is "0" at charge pump
current automatically switched mode , output is "1" at other mode.

Power on reset

The initial status are shown as below when supply voltage is turned on.
If supply voltage becomes less than about 3.0V, the initial status is set.

Byte	MSB							LSB
Divider Byte1 (DB1)	0	X	X	X	X	X	X	X
Divider Byte2 (DB2)	X	X	X	X	X	X	X	X
Control Byte (CB1)	1	1	0	1	X	1	1	1
Band Byte (CB2)	0	0	X	X	0	0	0	0

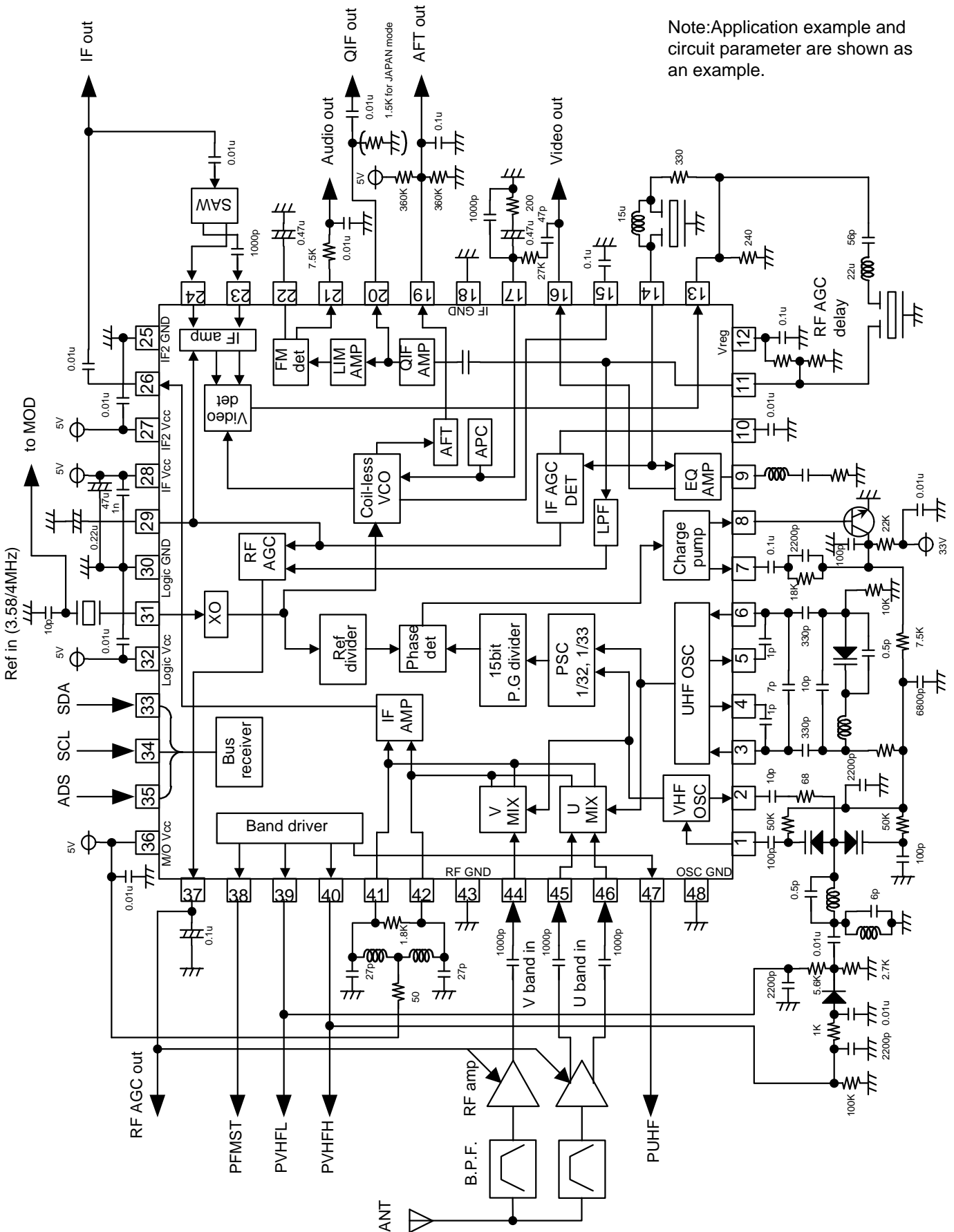
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APPLICATION EXAMPLE

Note:Application example and circuit parameter are shown as an example.



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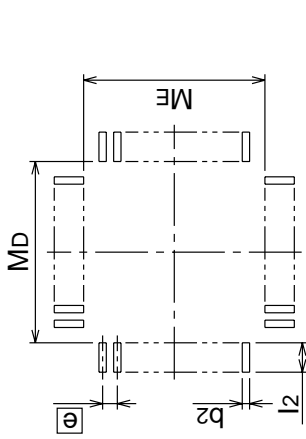
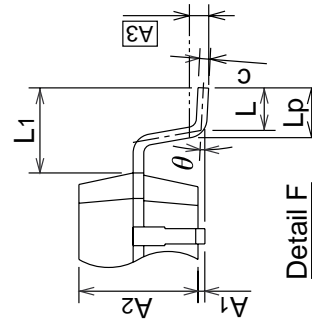
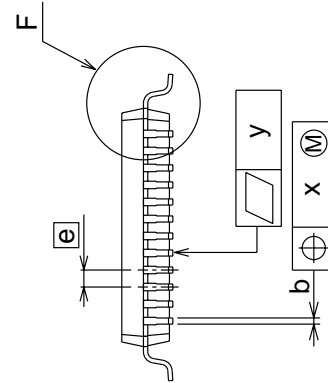
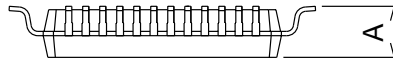
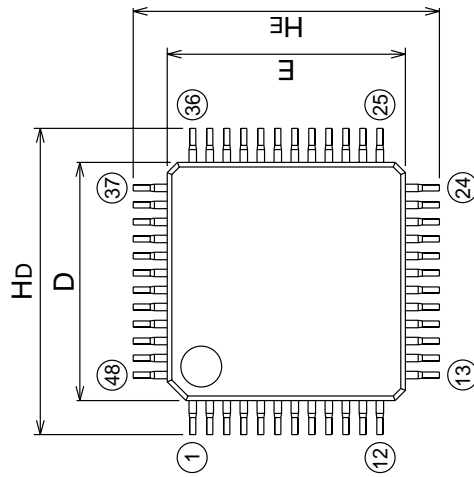
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DETAILED DIAGRAM OF PACKAGE OUTLINE

Plastic 48pin 7X7mm body LQFP

48P6Q-A (MMP)

EIAJ Package Code LQFP48-P-77-0.50	JEDEC Code -	Weight(g) -	Lead Material Cu Alloy
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Recommended Mount Pad

Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	-	-	1.7
A1	0	0.1	0.2
A2	-	1.4	-
b	0.17	0.22	0.27
c	0.105	0.125	0.175
D	6.9	7.0	7.1
E	6.9	7.0	7.1
e	-	0.5	-
HD	8.8	9.0	9.2
HE	8.8	9.0	9.2
L	0.35	0.5	0.65
L1	-	1.0	-
Lp	0.45	0.6	0.75
A3	-	0.25	-
x	-	-	0.08
y	-	-	0.1
θ	0°	-	8°
b2	-	0.225	-
I2	1.0	-	-
MD	-	7.4	-
ME	-	7.4	-

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